

[FLIP-CHIP SUBSTRATE AND FLIP-CHIP BONDING PROCESS THEREOF]

Abstract

A flip-chip substrate for bonding with a chip is provided. The chip has an active surface with a plurality of bonding pads and each bonding pad has a bump thereon. The flip-chip substrate has a plurality of contact pads that correspond in positions with the bonding pads on the chip such that the chip pads are aligned to their corresponding contact pads at the melting point of the bump material.